

TOSHIBA

TOSHIBA Original CMOS 16-Bit Microcontroller

TLCS-900/L Series

TMP93PW20A

TOSHIBA CORPORATION

Semiconductor Company

Preface

Thank you very much for making use of Toshiba microcomputer LSIs.
Before use this LSI, refer the section, "Points of Note and Restrictions".
Especially, take care below cautions.

****CAUTION****

How to release the HALT mode

Usually, interrupts can release all halts status. However, the interrupts = ($\overline{\text{NMI}}$, INT0 to INT4, INTKEY and INTRTC), which can release the HALT mode may not be able to do so if they are input during the period CPU is shifting to the HALT mode (for about 3 clocks of f_{FPH}) with IDLE1 or STOP mode (RUN and IDLE2 are not applicable to this case). (In this case, an interrupt request is kept on hold internally.)

If another interrupt is generated after it has shifted to HALT mode completely, halt status can be released without difficulty. The priority of this interrupt is compare with that of the interrupt kept on hold internally, and the interrupt with higher priority is handled first followed by the other interrupt.

Low Voltage/Low Power

CMOS 16-Bit Microcontroller TMP93PW20AF

1. Outline and Device Characteristics

The TMP93PW20A is OTP type MCU which includes 128 Kbytes one-time PROM. Using the adapter-socket, you can write and verify the data for the TMP93CS20 by general EPROM programmer.

The TMP93PW20A has the same pin-assignment as the TMP93CS20 (Mask ROM type). Writing the program to built-in PROM, the TMP93PW20A operates as the same way as the TMP93CS20.

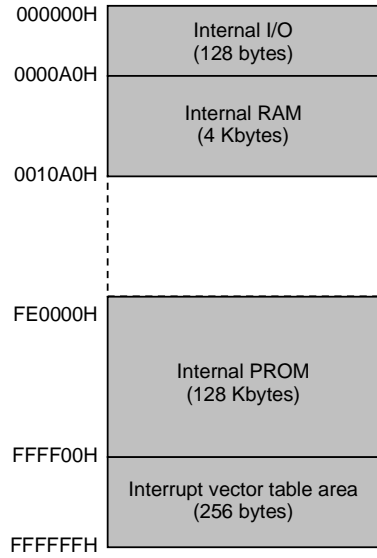
There are differences in the memory mapping area and the memory capacity of the internal PROM and RAM between the TMP93PW20A and the TMP93CS20. The internal PROM of the TMP93PW20A is 128 Kbytes, and the internal RAM is 4 Kbytes. The internal ROM of the TMP93CS20 is 64 Kbytes, and the internal RAM is 2 Kbytes. Memory maps are described as follows.

030619EBP1

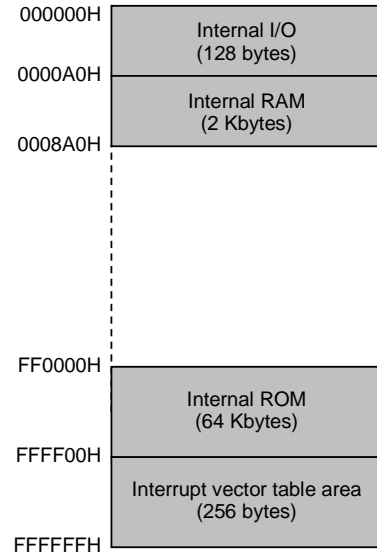
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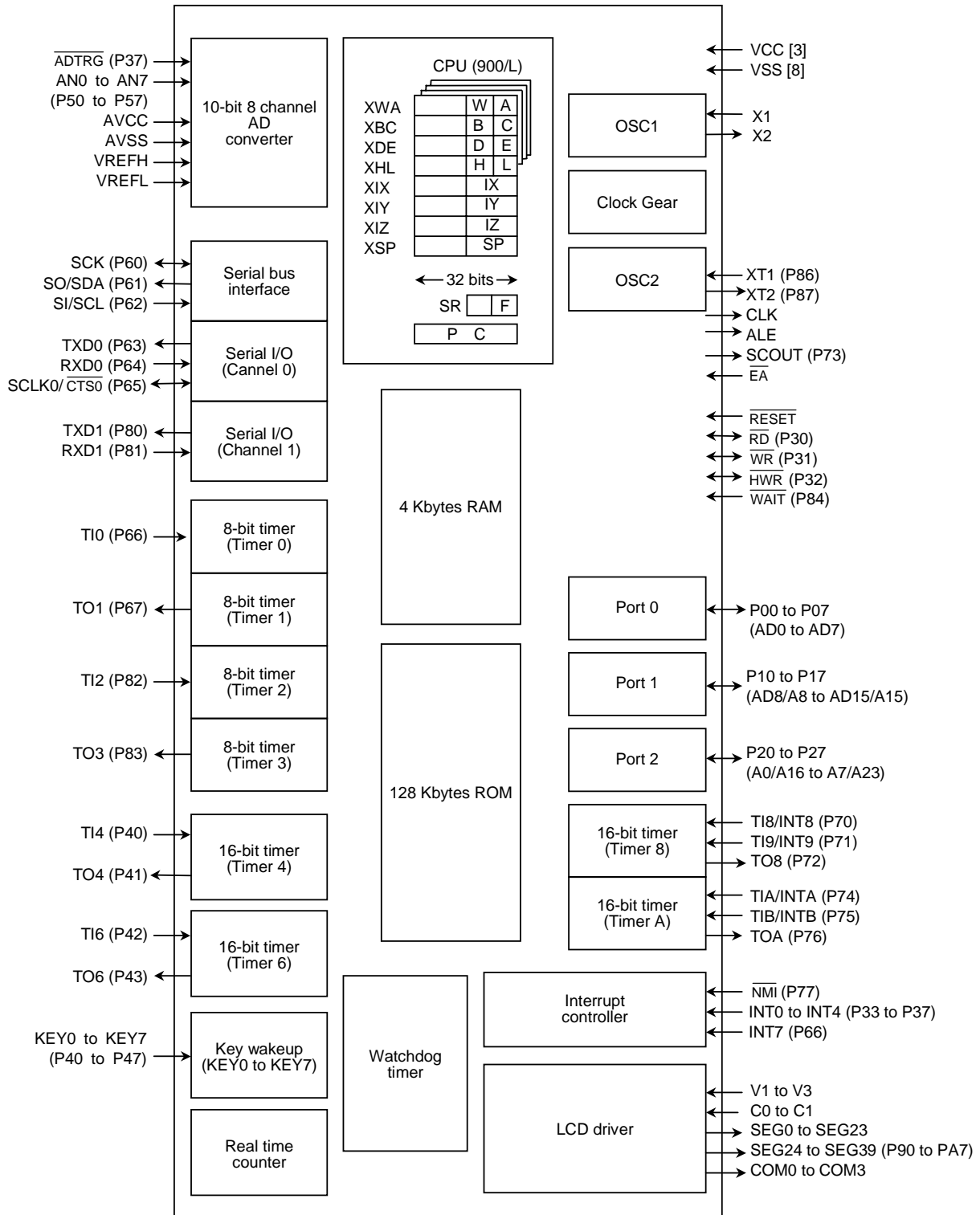


Memory map of TMP93PW20A



Memory map of TMP93CS20

Product No.	ROM	RAM	Package	Adapter Socket
TMP93PW20A	OTP 128 Kbytes	4 Kbytes	P-LQFP144-1616-0.40	BM11141



Note: The item in parentheses () are the initial setting after reset.

Figure 1.1 TMP93PW20A Block Diagram

2. Pin Assignment and Functions

The assignment of input/output pins for the TMP93PW20A their names and outline functions are described below.

2.1 Pin Assignment

Figure 2.1.1 shows pin assignment of the TMP93PW20AF.

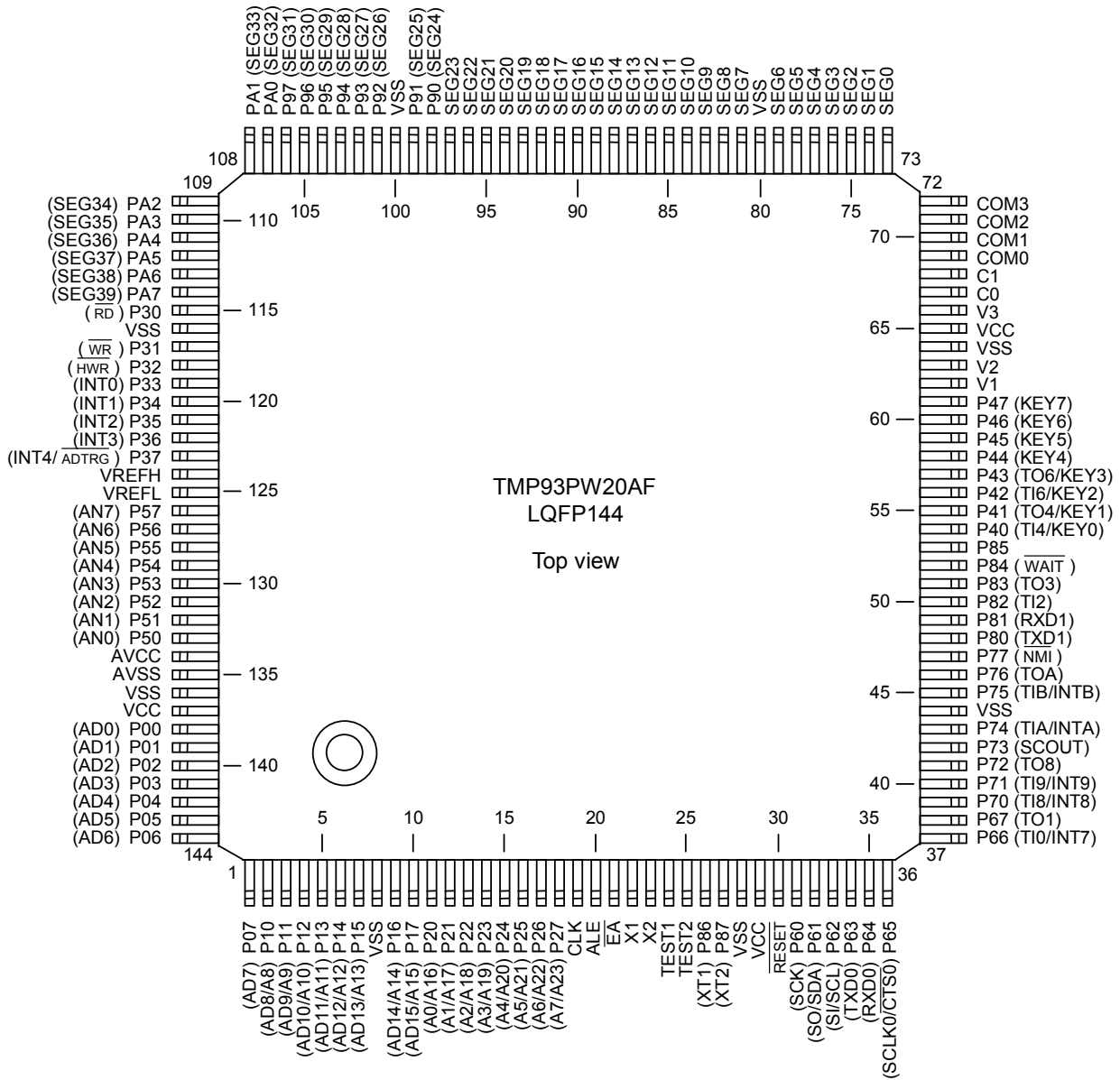


Figure 2.1.1 Pin Assignment (144-pin LQFP)

2.2 Pin Names and Functions

The TMP93PW20A has MCU mode and PROM mode.

(1) Pin functions of TMP93PW20A in MCU mode.

Table 2.2.1 Name and Function in MCU Mode (1/3)

Pin Names	Number of Pins	I/O	Functions
P00 to P07 AD0 to AD7	8	I/O I/O	Port 0: I/O port that allows I/O to be selected at the bit level. Address and data (lower): Bits 0 to 7 for address and data bus.
P10 to P17 AD8 to AD15 A8 to A15	8	I/O I/O Output	Port 1: I/O port that allows I/O to be selected at the bit level. Address and data (Upper): Bits 8 to 15 for address and data bus. Address: Bits 8 to 15 for address bus.
P20 to P27 A0 to A7 A16 to A23	8	I/O Output Output	Port 2: I/O port that allows I/O to be selected at the bit level (with pull-up resistor). Address: Bits 0 to 7 for address bus. Address: Bits 16 to 23 for address bus.
P30 \overline{RD}	1	Output Output	Port 30: Output port. Read: Strobe signal for reading external memory. (Read when reading internal memory at $P3<P30> = 0$, $P3FC<P30F> = 1$.)
P31 \overline{WR}	1	Output Output	Port 31: Output port. Write: Strobe signal for writing data on pins AD0 to AD7.
P32 \overline{HWR}	1	I/O Output	Port 32: I/O port (with pull-up resistor). High write: Strobe signal for writing data on pins AD8 to AD15.
P33 INT0	1	I/O Input	Port 33: I/O port (with pull-up resistor). Interrupt request pin 0: Interrupt request pin with programmable level/rising/falling edge.
P34 INT1	1	I/O Input	Port 34: I/O port (with pull-up resistor). Interrupt request pin 1: Interrupt request pin with programmable rising/falling edge.
P35 INT2	1	I/O Input	Port 35: I/O port (with pull-up resistor). Interrupt request pin 2: Interrupt request pin with programmable rising/falling edge.
P36 INT3	1	I/O Input	Port 36: I/O port (with pull-up resistor). Interrupt request pin 3: Interrupt request pin with programmable rising/falling edge.
P37 INT4 \overline{ADTRG}	1	I/O Input Input	Port 37: I/O port (with pull-up resistor). Interrupt request pin 4: Interrupt request pin with programmable rising/falling edge. ADTRG Input AD external trigger pin: External trigger pin to start AD conversion.
P40 TI4 KEY0	1	I/O Input Input	Port 40: I/O port (with pull-up resistor). Timer input 4: 16-bit timer 4 input. Key input 0: Key-on wakeup pin 0.
P41 TO4 KEY1	1	I/O Output Input	Port 41: I/O port (with pull-up resistor). Timer output 4: 16-bit timer 4 output. Key input 1: Key-on wakeup pin 1.
P42 TI6 KEY2	1	I/O Input Input	Port 42: I/O port (with pull-up resistor). Timer input 6: 16-bit timer 6 input. Key input 2: Key-on wakeup pin 2.
P43 TO6 KEY3	1	I/O Output Input	Port 43: I/O port (with pull-up resistor). Timer output 6: 16-bit timer 6 output. Key input 3: Key-on wakeup pin 3.
P44 to P47 KEY4 to KEY7	4	I/O Input	Port 44 to 47: I/O port (with pull-up resistor). Key input 4 to 7: Key-on wakeup pin 4 to 7.
P50 to P57 AN0 to AN7	8	Input Input	Port 50 to 57: Pin used to input port. Analog input 0 to 7.

Table 2.2.1 Name and Function in MCU Mode (2/3)

Pin Names	Number of Pins	I/O	Functions
P60 SCK	1	I/O I/O	Port 60: I/O port. Clock I/O pin in SIO mode of the serial bus interface.
P61 SO SDA	1	I/O Output I/O	Port 61: I/O port (with programmable open drain). Data send channel in SIO mode of the serial bus interface. Data I/O pin in I ² C bus mode of the serial bus interface.
P62 SI SCL	1	I/O Input I/O	Port 62: I/O port (with programmable open drain). Data receive channel in SIO mode of the serial bus interface. Clock I/O pin in I ² C bus mode of the serial bus interface.
P63 TXD0	1	I/O Output	Port 63: I/O port (with programmable open drain). Serial send data 0.
P64 RXD0	1	I/O Input	Port 64: I/O port. Serial receive data 0.
P65 SCLK0 $\overline{\text{CTS0}}$	1	I/O I/O Input	Port 65: I/O port. Serial clock I/O 0. Serial data send enable 0 (Clear to send).
P66 TI0 INT7	1	I/O Input Input	Port 66: I/O port. Timer input 0: 8-bit timer 0 input. Interrupt request pin 7: Interrupt request pin with programmable rising/falling edge.
P67 TO1	1	I/O Output	Port 67: I/O port. Timer output1: 8-bit timer 0 or timer 1 output.
P70 TI8 INT8	1	I/O Input Input	Port 70: I/O port (with pull-up resistor). Timer input 8: 16-bit timer 8 input. Interrupt request pin 8: Interrupt request pin with programmable rising/falling edge.
P71 TI9 INT9	1	I/O Input Input	Port 71: I/O port (with pull-up resistor). Timer input 9: 16-bit timer 8 input. Interrupt request pin 9: Interrupt request pin with rising edge.
P72 TO8	1	I/O Output	Port 72: I/O port (with pull-up resistor). Timer output 8: 16-bit timer 8 output.
P73 SCOUT	1	I/O Output	Port 73: I/O port (with pull-up resistor). System clock output: System clock or double system clock output to be synchronized with the external circuit.
P74 TIA INTA	1	I/O Input Input	Port 74: I/O port (with pull-up resistor). Timer input A: 16-bit timer A input. Interrupt request pin A: Interrupt request pin with programmable rising/falling edge.
P75 TIB INTB	1	I/O Input Input	Port 75: I/O port (with pull-up resistor). Timer input B: 16-bit timer B input. Interrupt request pin B: Interrupt request pin with rising edge.
P76 TOA	1	I/O Output	Port 76: I/O port (with pull-up resistor). Timer output A: 16-bit timer A output.
P77 $\overline{\text{NMI}}$	1	I/O Input	Port 77: I/O port (with pull-up resistor). Non-maskable interrupt request pin: Interrupt request pin with programmable falling edge or both edges.
P80 TXD1	1	I/O Output	Port 80: I/O port (with programmable open drain). Serial send data 1.
P81 RXD1	1	I/O Input	Port 81: I/O port (with programmable open drain). Serial receive data 1.
P82 TI2	1	I/O Input	Port 82: I/O port (with programmable open drain). Timer input 2: 8-bit timer 2 input pin.
P83 TO3	1	I/O Output	Port 83: I/O port (with programmable open drain). Timer output 3: 8-bit timer 2, 3 output pin.
P84 $\overline{\text{WAIT}}$	1	I/O Input	Port 84: I/O port (with programmable open drain). Wait: Pin used to request CPU bus wait.

Table 2.2.1 Name and Function in MCU Mode (3/3)

Pin Names	Number of Pins	I/O	Functions
P85	1	I/O	Port 85: I/O port (with programmable open drain).
P86 XT1	1	I/O Input	Port 86: I/O port (Open drain). Low-frequency oscillator connecting pin.
P87 XT2	1	I/O Output	Port 87: I/O port (Open drain). Low-frequency oscillator connecting pin.
P90 to P97 SEG24 to SEG31	8	Output Output	Port 90 to port 97: Output port (Open drain). Segment data output pin.
PA0 to PA7 SEG32 to SEG39	8	Output Output	Port A0 to A7: Output port, large current port (Open drain). LCD segment output pin.
SEG0 to SEG23	24	Output	LCD segment output.
COM0 to COM3	4	Output	LCD common output.
AVCC	1	Power supply	Power supply pin for AD converter.
AVSS	1	Power supply	GND pin for AD converter (0 V).
VREFH	1	Input	Pin for reference voltage input to AD converter (H).
VREFL	1	Input	Pin for reference voltage input to AD converter (L).
X1	1	Input	Oscillator connecting pin.
X2	1	Output	Oscillator connecting pin.
$\overline{\text{RESET}}$	1	Input	Reset: Initializes LSI.
ALE	1	Output	Address latch enable. Can be disabled for reducing noise.
CLK	1	Output	Clock output: Outputs "external input clock $\times 1 \div 4$ " clock. Pulled-up during reset. Can be disabled for reducing noise.
$\overline{\text{EA}}$	1	Input	The VCC pin should be connected.
VCC	3	Power supply	Power supply pin (All Vcc pins should be connected with the power supply pin).
VSS	8	Power supply	GND pin (0 V) (All Vss pins should be connected with GND (0 V)).
TEST1 TEST2	2	Output Input	TEST1 should be connected with TEST2 pin. Do not connect to any other pins.
C0, C1, V1 to V3	5	LCD pin	LCD drive boosting pin. A condenser should be connected between C0 and C1, V1, V2, V3 and GND.

Note: All pins that have built-in pull-up resistors can be disconnected from the built-in pull-up resistor by software.

(2) Pin function of the TMP93PW20A in PROM mode

Pin names and functions are shown in Table 2.2.2.

Table 2.2.2 Pin Names and Function in PROM Mode

Pin Names	Number of Pins	Input/Output	Functions	Pin Names (in MCU mode)
A7 to A0	8	Input	Memory address of program	P27 to P20
A15 to A8	8	Input		P17 to P10
A16	1	Input		P67
D7 to D0	8	I/O	Memory data of program	P07 to P00
\overline{CE}	1	Input	Chip enable	P32
\overline{OE}	1	Input	Output control	P30
PGM	1	Input	Program control	P31
VPP	1	Power supply	12.75 V/5 V (Power supply of program)	\overline{EA}
VCC	4	Power supply	6.25 V/5 V	VCC, AVCC
VSS	9	Power supply	0 V	VSS, AVSS
Pin Names	Number of Pins	Input/Output	Pin State	
P60	1	Input	Fix to low level (Security pin)	
\overline{RESET}	1	Input	Fix to low level (PROM mode)	
CLK	1	Input		
ALE	1	Output	Open	
X1	1	Input	Self oscillation with resonator	
X2	1	Output		
P66 to P61	6	Input	Fix to high level	
TEST1 TEST2	2	Output Input	TEST1 should be connected with TEST2 pin Do not connect to any other pins	
P37 to P33 P47 to P40 P57 to P50 P77 to P70 P87 to P80 P97 to P90 PA7 to PA0 SEG23 to SEG0 VREFH VREFL C0, C1 COM3 to COM0 V3 to V1	88	I/O	Open	

3. Operation

This section describes the functions and basic operational blocks of the TMP93PW20A.

The TMP93PW20A has PROM in place of the mask ROM which is included in the TMP93CS20. The other configuration and functions are the same as the TMP93CS20. Regarding the function of the TMP93PW20A, which is not described herein, see the TMP93CS20.

The TMP93PW20A has two operational modes: MCU mode and PROM mode.

3.1 MCU mode

(1) Mode setting and function

The MCU mode is set by releasing the CLK pin (Pin open).

In the MCU mode, the operation is the same as TMP93CS20.

(2) Memory map

The memory map of TMP93PW20A differs from that of TMP93CS20.

The memory map in MCU mode is shown in Figure 3.1.1, and the memory map in PROM mode is shown in Figure 3.1.2.

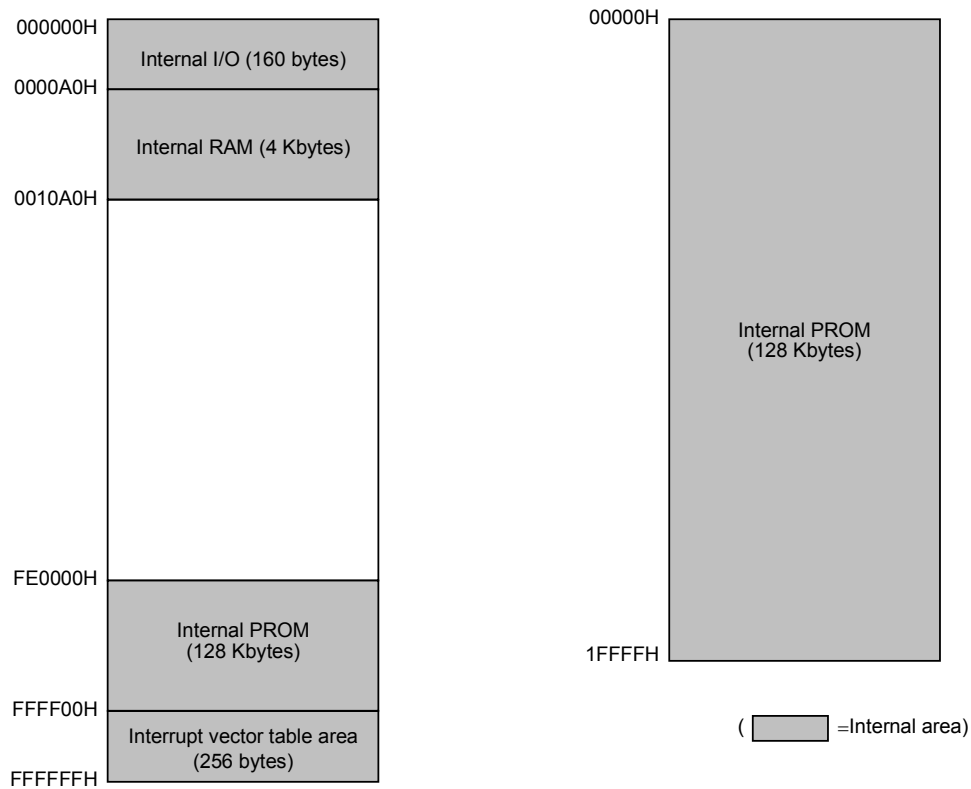


Figure 3.1.1 Memory Map in MCU Mode

Figure 3.1.2 Memory Map in PROM Mode

(3) Note on setting of the wait controller

The TMP93PW20A has a wide memory area compared as the TMP93CS20. For the addressing area of WAITC1, there is a difference between the TMP93PW20A and the TMP93CS20.

When bits 1 and 0 < B1C1:0> in the chip select and wait control register 1 (WAITC1) is set to 00, the address area is specified as follows.

TMP93PW20A	TMP93CS20
10A0H to 7FFFH	8A0H to 7FFFH

3.2 PROM Mode

(1) Mode setting and programming

PROM mode is set by setting the $\overline{\text{RESET}}$ and CLK pins to the “Low” level.

The programming and verification for the internal PROM is achieved by using a general PROM programmer with the adaptor socket.

1. OTP adaptor

BM11141: TMP93PW20AF adaptor

2. Setting OTP adaptor

Set the switch (SW1) to N side.

3. Setting PROM programmer

i) Set PROM type to TC571000D.

Size: 1 Mbits (128 K × 8 bits)

VPP: 12.75 V

tPW: 100 μs

Electric signature function: None

ii) Transferring the data (Copy)

In TMP93PW20AF, PROM is placed on addresses 00000H to 1FFFFH in PROM mode, and addresses FE0000H to FFFFFFFH in MCU mode.

Therefore data should be transferred to addresses 00000H to 1FFFFH in PROM mode using the object converter (tuconv) or the block transfer mode. (See instruction manual of PROM programmer.)

iii) Setting program address

Start address: 00000H

End address: 1FFFFH

4. Programming

Program/verify according to the procedures of PROM programmer.

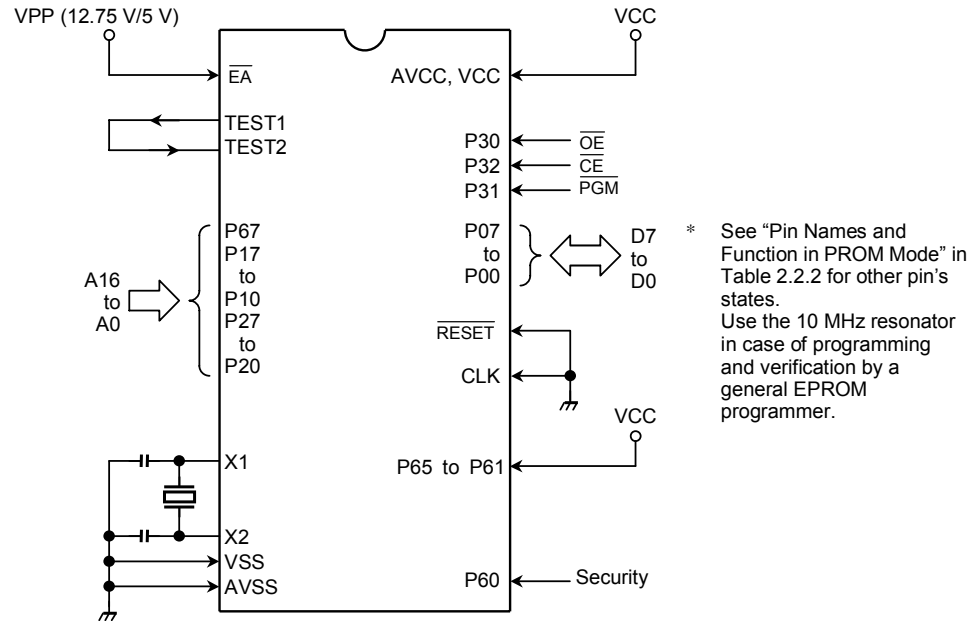


Figure 3.2.1 Pin Setting in PROM Mode

(2) Note on electric signature

The electric signature mode (Hereinafter referred to as “signature”) is not supported in the TMP93PW20A. Therefore using signature with PROM programmer applies voltage of 12 ± 0.5 V to pin 9 (A9) of the address, and the device is damaged. Do not use signature.

(3) Program mode

The TMP93PW20A is provided with all bits set to 1 (OFF). When programming it, write data 0 to necessary bit locations.

Applying $V_{PP} = 12.5$ V, $\overline{OE} = V_{IH}$ $\overline{CE} = V_{IL}$ enables writing data.

The one-time PROM which is included in the TMP93PW20A can write data in any order. It is possible to write a special address.

(4) Adapter socket (BM11141)

The BM11141 is an adapter socket to write data to the one-time PROM in the TMP93PW20A using a general PROM programmer.

(5) Program storage area in PROM mode

The TMP93PW20A has a program area (FE0000H to FFFFFFFH) of 128 Kbytes. In PROM mode, addresses 00000H to 1FFFFFFH correspond to addresses FE0000H to FFFFFFFH in MCU mode.

(6) How to program with a general PROM programmer

The PROM programmer should be equivalent to TC571000D.

1. Set a switch (SW1) of BM11141 to a program side (NOR). (BM11141 is hereinafter referred as an adapter.) (Note 1)
2. Set a MCU to the adapter. (Note 2)
3. Set the adapter to the PROM programmer. (Note 2)
4. Specify TC571000D as a type of the PROM.
5. Set a start address to 00000H and an end address to 1FFFFH to write the PROM. (Note 3)
6. Write the one-time PROM and verify according to operational procedures of the PROM programmer.

Note 1: If you write a data to the one-time PROM without setting the switch (SW1) to the program side, a device should be damaged.

Note 2: 1 pin marked on the socket of the PROM programmer must be matched to the 1 pin of the adapter. If you set them in reverse, the MCU or the PROM programmer should be damaged.

Note 3: When data 0 is written to an address over 1FFFFH, there is a possibility that the data is written to addresses 00000H to 1FFFFH and an original program is corrupted.

(7) Programming flow chart

The programming mode is set by applying 12.75 V (programming voltage) to the VPP pin when the following pins are set as follows, (VCC: 6.25 V, $\overline{\text{RESET}}$: "Low" level, CLK: "Low" level).

While address and data are fixed and $\overline{\text{CE}}$ pin is set to "L" level, 0.1 ms of "Low" level pulse is applied to PGM pin to program the data.

Then the data in the address is verified.

If the programmed data is incorrect, another 0.1 ms pulse is applied to $\overline{\text{PGM}}$ pin.

This programming procedure is repeated until correct data is read from the address (25 times maximum).

Subsequently, all data are programmed in all addresses.

The verification for all data is done under the condition of $V_{PP} = V_{CC} = 5 \text{ V}$ after all data were written.

Figure 3.2.2 shows the programming flowchart.

High Speed Program Writing.

Flowchart

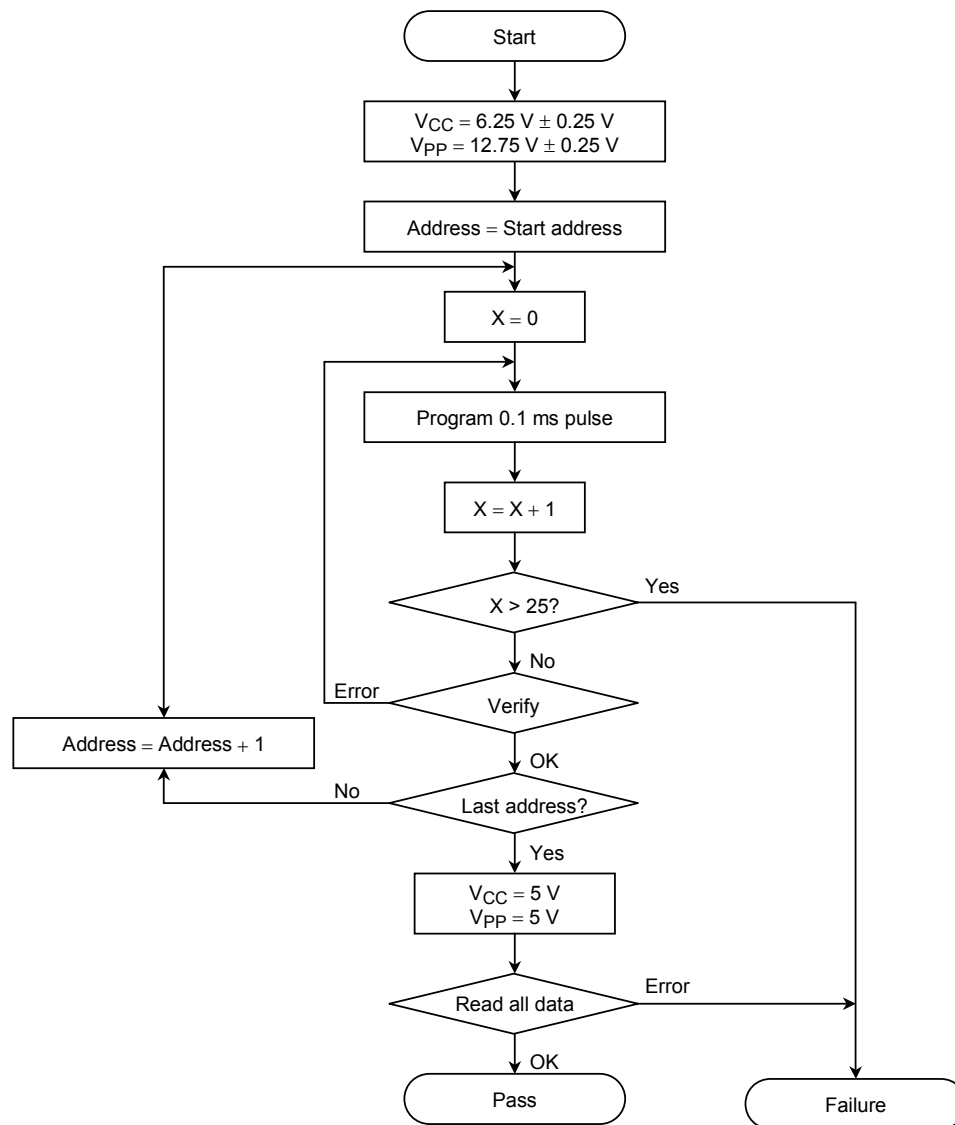


Figure 3.2.2 Flowchart

(8) Security bit

The TMP93PW20A has a security bit.

If the security bit is programmed to 0, the content of the PROM can not be read in PROM mode. (Outputs data FFH)

(How to program the security bit)

The difference from the programming procedures described in section 3.2 (1) are follows.

1. Setting OTP adapter

Set the switch (SW1) to S side.

2. Setting PROM programmer

i) Transferring the data

ii) Setting programming address

The security bit is in bit 0 of address 00000H.

Set the start address 00000H and the end address 00000H.

Set the data FEH at the address 00000H.

4. Electrical Characteristics

4.1 Maximum Rating (TMP93PW20A)

"X" used in an expression shows a frequency for the clock f_{FPH} selected by SYSCR1<SYSCK>. The value of X changes according to whether a clock gear or a low speed oscillator is selected. An example value is calculated for f_c , with gear = $f_c/1$ (SYSCR1<SYSCK, GEAR2:0> = 0000).

Parameter	Symbol	Rating	Unit
Power supply voltage	V_{CC}	-0.5 to 6.5	V
Input voltage	V_{IN}	Except \overline{EA} pin	
		\overline{EA} pin	-0.5 to 14.0
Output current (Per one pin), large current port	I_{OL1}	20	mA
Output current (Per one pin)	I_{OL2}	2	
Output current (Total of large current port)	ΣI_{OL1}	80	
Output current (Total)	ΣI_{OL}	120	
Output current (Total)	ΣI_{OH}	-80	
Power dissipation ($T_a = 85^\circ\text{C}$)	P_D	600	mW
Soldering temperature (10 s)	T_{SOLDER}	260	°C
Storage temperature	T_{STG}	-65 to 150	
Operating temperature	T_{OPR}	-40 to 85	

Note: The maximum ratings are rated values which must not be exceeded during operation, even for an instant. Any one of the ratings must not be exceeded. If any maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no maximum rating value will ever be exceeded.

4.2 DC Characteristics (1/2)

$T_a = -40$ to 85°C

Parameter		Symbol	Condition	Min	Typ. (Note)	Max	Unit
Power supply voltage ($AV_{CC} = V_{CC}$ $AV_{SS} = V_{SS} = 0\text{ V}$)		V_{CC}	$f_c = 4$ to 20 MHz	4.5		5.5	V
			$f_c = 4$ to 12.5 MHz	2.7			
Input low voltage	AD0 to AD15	V_{IL}	$V_{CC} \geq 4.5\text{ V}$	-0.3		0.8	V
		V_{IL1}	$V_{CC} < 4.5\text{ V}$			0.6	
	Port	V_{IL1}	$V_{CC} = 2.7$ to 5.5 V			$0.3 V_{CC}$	
	KEY0 to KEY7, NMI, INT0 to INT4	V_{IL2}				$0.25 V_{CC}$	
	\overline{EA}	V_{IL3}				0.3	
	X1	V_{IL4}				$0.2 V_{CC}$	
	V_{IL5}	$0.1 V_{CC}$					
Input high voltage	AD0 to AD15	V_{IH}	$V_{CC} \geq 4.5\text{ V}$	2.2		$V_{CC} + 0.3$	V
		V_{IH}	$V_{CC} \geq 4.5\text{ V}$	2.0			
	Port	V_{IH1}	$V_{CC} = 2.7$ to 5.5 V	$0.7 V_{CC}$			
	KEY0 to KEY7, NMI, INT0 to INT4	V_{IH2}		$0.75 V_{CC}$			
	\overline{EA}	V_{IH3}		$V_{CC} - 0.3$			
	X1	V_{IH4}		$0.8 V_{CC}$			
	V_{IH5}	$0.6 V_{CC}$					

Note: Typical values are for $T_a = 25^\circ\text{C}$ and $V_{CC} = 5\text{ V}$ unless otherwise noted.

4.2 DC Characteristics (2/2)

Parameter	Symbol	Condition	Min	Typ. (Note 1)	Max	Unit	
Output low voltage	V_{OL}	$I_{OL} = 1.6 \text{ mA}$ ($V_{CC} = 2.7 \text{ to } 5.5 \text{ V}$)			0.45	V	
Output low current (PA0 to PA7)	I_{OLA}	$V_{OL} = 1.0 \text{ V}$ ($V_{CC} = 5 \text{ V} \pm 10\%$)	16			mA	
		($V_{CC} = 3 \text{ V} \pm 10\%$)	7				
Output high voltage	V_{OH1}	$I_{OH} = -400 \mu\text{A}$ ($V_{CC} = 3 \text{ V} \pm 10\%$)	2.4			V	
	V_{OH2}	$I_{OH} = -400 \mu\text{A}$ ($V_{CC} = 5 \text{ V} \pm 10\%$)	4.2				
Darlington drive current (8 output pins max)	I_{DAR} (Note 2)	$V_{EXT} = 1.5 \text{ V}$ $R_{EXT} = 1.1 \text{ k}\Omega$ ($V_{CC} = 5 \text{ V} \pm 10\%$ only)	-1.0		-3.5	mA	
Input leakage current	I_{LI}	$0.0 \leq V_{IN} \leq V_{CC}$		0.02	± 5	μA	
Output leakage current	I_{LO}	$0.2 \leq V_{IN} \leq V_{CC} - 0.2$		0.05	± 10		
Power down voltage (at stop, RAM backup)	V_{STOP}	$V_{IL2} = 0.2 V_{CC}$, $V_{IH2} = 0.8 V_{CC}$	2.0		6.0	V	
Pin capacitance	C_{IO}	$f_c = 1 \text{ MHz}$			10	pF	
Shumitt width KEYx, NMI, INT0 to INT4, RESET	V_{TH}		0.4	1.0		V	
Programmable pull-up resistance	R_{KH}	$V_{CC} = 5 \text{ V} \pm 10\%$	50		150	k Ω	
		$V_{CC} = 3 \text{ V} \pm 10\%$	100		300		
NORMAL	I_{CC}	$V_{CC} = 5 \text{ V} \pm 10\%$ $f_c = 20 \text{ MHz}$		32	40	mA	
RUN				24	30		
IDLE2				17	21		
IDLE1				4.5	7		
NORMAL		$V_{CC} = 3 \text{ V} \pm 10\%$ $f_c = 12.5 \text{ MHz}$ (Typ. $V_{CC} = 3.0 \text{ V}$)		14	20	mA	
RUN				10	14		
IDLE2				7	10		
IDLE1				2	3		
SLOW		$V_{CC} = 3 \text{ V} \pm 10\%$ $f_s = 32.768 \text{ kHz}$ (Typ. $V_{CC} = 3.0 \text{ V}$) at boosting frequency = 1 kHz		40	55	μA	
RUN				30	42		
IDLE2				20	33		
IDLE1				10	24		
STOP			$T_a \leq 50^\circ\text{C}$		0.2	10	μA
			$T_a \leq 70^\circ\text{C}$			20	
			$T_a \leq 85^\circ\text{C}$			50	

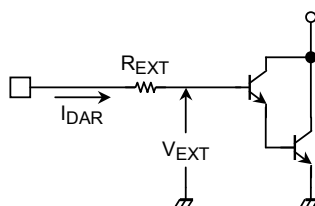
Note 1: Typical values are for $T_a = 25^\circ\text{C}$ and $V_{CC} = 5 \text{ V}$ unless otherwise noted.

Note 2: I_{DAR} is guaranteed for up to eight ports.

Note 3: Segment or common output is not loaded.

Note 4: I_{CC} measurement conditions (NORMAL, SLOW): Only CPU is operational; output pins are open and input pins are fixed.

(e.g.) Diagram of I_{DAR}



4.3 AC Electrical Characteristics

(1) $V_{CC} = 5\text{ V} \pm 10\%$

No.	Parameter	Symbol	Variable		16 MHz		20 MHz		Unit
			Min	Max	Min	Max	Min	Max	
1	Osc. period (= x)	t_{OSC}	50	31250	62.5		50		ns
2	CLK width	t_{CLK}	$2x - 40$		85		60		ns
3	A0 to A23 valid \rightarrow CLK hold	t_{AK}	$0.5x - 20$		11		5		ns
4	CLK valid \rightarrow A0 to A23 hold	t_{KA}	$1.5x - 70$		24		5		ns
5	A0 to A15 valid \rightarrow ALE fall	t_{AL}	$0.5x - 15$		16		10		ns
6	ALE fall \rightarrow A0 to A15 hold	t_{LA}	$0.5x - 20$		11		5		ns
7	ALE high width	t_{LL}	$x - 40$		23		10		ns
8	ALE fall \rightarrow \overline{RD} / \overline{WR} fall	t_{LC}	$0.5x - 25$		6		0		ns
9	\overline{RD} / \overline{WR} rise \rightarrow ALE rise	t_{CL}	$0.5x - 20$		11		5		ns
10	A0 to A15 valid \rightarrow \overline{RD} / \overline{WR} fall	t_{ACL}	$x - 25$		38		25		ns
11	A0 to A23 valid \rightarrow \overline{RD} / \overline{WR} fall	t_{ACH}	$1.5x - 50$		44		25		ns
12	\overline{RD} / \overline{WR} rise \rightarrow A0 to A23 hold	t_{CA}	$0.5x - 25$		6		0		ns
13	A0 to A15 valid \rightarrow D0 to D15 input	t_{ADL}		$3.0x - 55$		133		95	ns
14	A0 to A23 valid \rightarrow D0 to D15 input	t_{ADH}		$3.5x - 65$		154		110	ns
15	\overline{RD} fall \rightarrow D0 to D15 input	t_{RD}		$2.0x - 60$		65		40	ns
16	\overline{RD} low pulse width	t_{RR}	$2.0x - 40$		85		60		ns
17	\overline{RD} rise \rightarrow D0 to D15 hold	t_{HR}	0		0		0		ns
18	\overline{RD} rise \rightarrow A0 to A15 output	t_{RAE}	$x - 15$		48		35		ns
19	\overline{WR} low pulse width	t_{WW}	$2.0x - 40$		85		60		ns
20	D0 to D15 valid \rightarrow \overline{WR} rise	t_{DW}	$2.0x - 55$		70		45		ns
21	\overline{WR} rise \rightarrow D0 to D15 hold	t_{WD}	$0.5x - 15$		16		10		ns
22	A0 to A23 valid \rightarrow \overline{WAIT} input	t_{AWH}		$3.5x - 90$		129		85	ns
23	A0 to A15 valid \rightarrow \overline{WAIT} input	t_{AWL}		$3.0x - 80$		108		70	ns
24	\overline{RD} / \overline{WR} fall \rightarrow \overline{WAIT} hold	t_{CW}	$2.0x + 0$		125		100		ns
25	A0 to A23 valid \rightarrow Port input	t_{APH}		$2.5x - 120$		36		5	ns
26	A0 to A23 valid \rightarrow Port hold	t_{APH2}	$2.5x + 50$		206		175		ns
27	\overline{WR} rise \rightarrow Port valid	t_{CP}		200		200		200	ns

AC measuring conditions

- Output level: High 2.2 V/Low 0.8 V, $CL = 50\text{ pF}$
(However, $CL = 100\text{ pF}$ for AD0 to AD15, A0 to A23, ALE, \overline{RD} , \overline{WR} , \overline{HWR} , CLK)
- Input level: High 2.4 V/Low 0.45 V (AD0 to AD15)
High $0.8 \times V_{CC}$ /Low $0.2 \times V_{CC}$ (except AD0 to AD15)

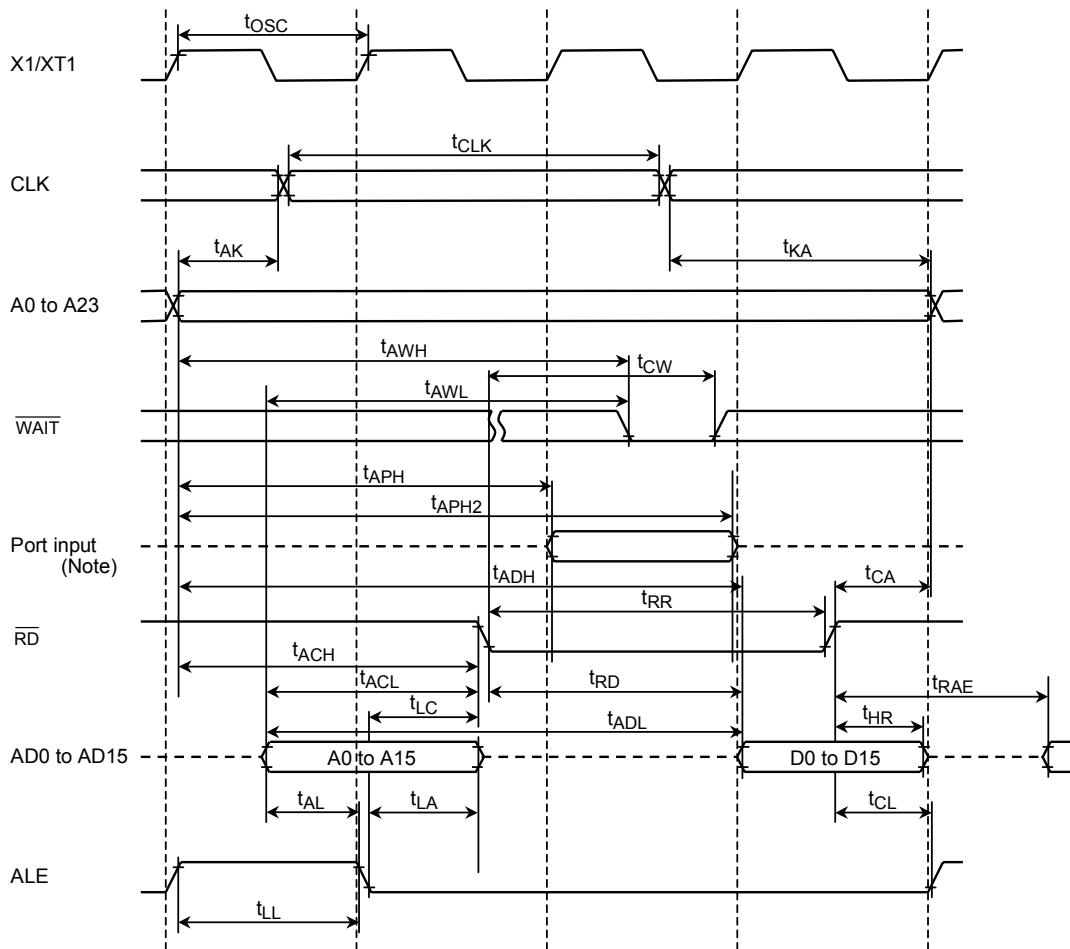
(2) $V_{CC} = 3\text{ V} \pm 10\%$

No.	Parameter	Symbol	Variable		12.5 MHz		Unit
			Min	Max	Min	Max	
1	Osc. period (= x)	t_{OSC}	80	31250	80		ns
2	CLK width	t_{CLK}	$2x - 40$		120		ns
3	A0 to A23 valid → CLK hold	t_{AK}	$0.5x - 30$		10		ns
4	CLK valid → A0 to A23 hold	t_{KA}	$1.5x - 80$		40		ns
5	A0 to A15 valid → ALE fall	t_{AL}	$0.5x - 35$		5		ns
6	ALE fall → A0 to A15 hold	t_{LA}	$0.5x - 35$		5		ns
7	ALE high width	t_{LL}	$x - 60$		20		ns
8	ALE fall → $\overline{RD} / \overline{WR}$ fall	t_{LC}	$0.5x - 35$		5		ns
9	$\overline{RD} / \overline{WR}$ rise → ALE rise	t_{CL}	$0.5x - 40$		0		ns
10	A0 to A15 valid → $\overline{RD} / \overline{WR}$ fall	t_{ACL}	$x - 50$		30		ns
11	A0 to A23 valid → $\overline{RD} / \overline{WR}$ fall	t_{ACH}	$1.5x - 50$		70		ns
12	$\overline{RD} / \overline{WR}$ rise → A0 to A23 hold	t_{CA}	$0.5x - 40$		0		ns
13	A0 to A15 valid → D0 to D15 input	t_{ADL}		$3.0x - 110$		130	ns
14	A0 to A23 valid → D0 to D15 input	t_{ADH}		$3.5x - 125$		155	ns
15	\overline{RD} fall → D0 to D15 input	t_{RD}		$2.0x - 115$		45	ns
16	\overline{RD} low pulse width	t_{RR}	$2.0x - 40$		120		ns
17	\overline{RD} rise → D0 to D15 hold	t_{HR}	0		0		ns
18	\overline{RD} rise → A0 to A15 output	t_{RAE}	$x - 25$		55		ns
19	\overline{WR} low pulse width	t_{WW}	$2.0x - 40$		120		ns
20	D0 to D15 valid → \overline{WR} rise	t_{DW}	$2.0x - 120$		40		ns
21	\overline{WR} rise → D0 to D15 hold	t_{WD}	$0.5x - 40$		0		ns
22	A0 to A23 valid → \overline{WAIT} input	t_{AWH}		$3.5x - 130$		150	ns
23	A0 to A15 valid → \overline{WAIT} input	t_{AWL}		$3.0x - 100$		140	ns
24	$\overline{RD} / \overline{WR}$ fall → \overline{WAIT} hold	t_{CW}	$2.0x + 0$		160		ns
25	A0 to A23 valid → Port input	t_{APH}		$2.5x - 120$		80	ns
26	A0 to A23 valid → Port hold	t_{APH2}	$2.5x + 50$		250		ns
27	\overline{WR} rise → Port valid	t_{CP}		200		200	ns

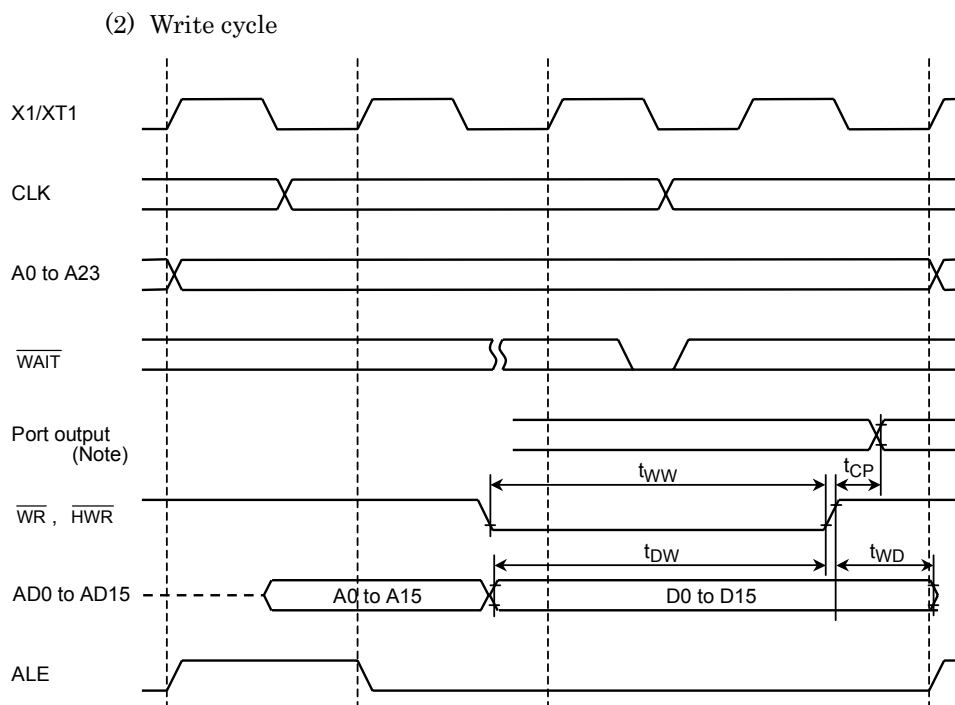
AC measuring conditions

- Output level: High $0.7 \times V_{CC}$ /Low $0.3 \times V_{CC}$, $CL = 50\text{ pF}$
- Input level: High $0.9 \times V_{CC}$ /Low $0.1 \times V_{CC}$

(1) Read cycle



Note: Since the CPU accesses the internal area to read data from a port, the control signals of external pins such as \overline{RD} and \overline{CS} are not enabled. Therefore, the above waveform diagram should be regarded as depicting internal operation. Please also note that the timing and AC characteristics of port input/output shown above are typical representation. For details, contact your local Toshiba sales representative.



Note: Since the CPU accesses the internal area to write data to a port, the control signals of external pins such as \overline{WR} and \overline{CS} are not enabled. Therefore, the above waveform diagram should be regarded as depicting internal operation. Please also note that the timing and AC characteristics of port input/output shown above are typical representation. For details, contact your local Toshiba sales representative.

4.4 Serial Channel Timing

(1) I/O interface mode

1. SCLK input mode

Parameter	Symbol	Variable		32.768 MHz (Note)		12.5 MHz		20 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
SCLK cycle	t_{SCY}	16x		488 μ s		1.28		0.8		μ s
Output data → SCLK rising edge or falling edge*	t_{OSS}	$t_{SCY}/2 - 5x - 50$		91.5 μ s		190		100		ns
SCLK rising edge or falling edge* → Output data hold	t_{OHS}	5x - 100		152 μ s		300		150		ns
SCLK rising edge or falling edge* → Input data hold	t_{HSR}	0		0		0		0		ns
SCLK rising edge or falling edge* → Effective data input	t_{SRD}		$t_{SCY} - 5x - 100$		336 μ s		780		450	ns

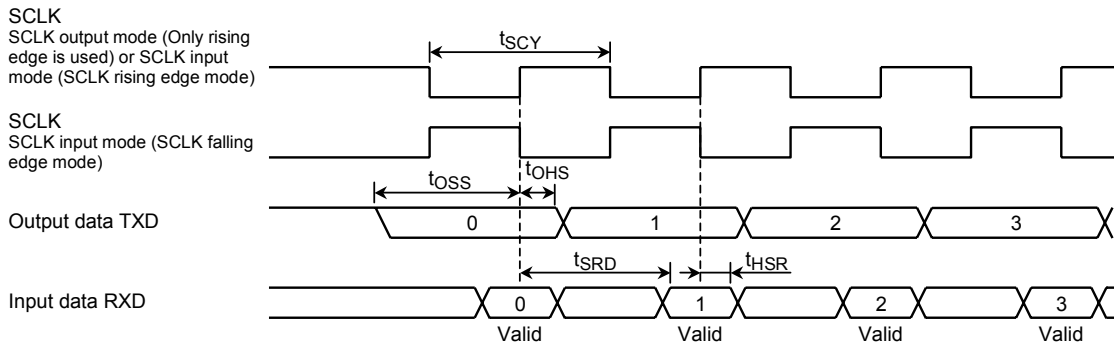
Note: System clock is fs, or input clock to prescaler is divisor clock of fs.

*) The rising edge is used in SCLK Rising mode.
The falling edge is used in SCLK Falling mode.

2. SCLK output mode

Parameter	Symbol	Variable		32.768 kHz (Note)		12.5 MHz		20 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
SCLK cycle (Programmable)	t_{SCY}	16x	8192x	488 μ s	250 ms	1.28	655.36	0.8	409.6	μ s
Output data → SCLK rising edge	t_{OSS}	$t_{SCY} - 2x - 150$		427 μ s		970		550		ns
SCLK rising edge → Output data hold	t_{OHS}	2x - 80		60 μ s		80		20		ns
SCLK rising edge → Input data hold	t_{HSR}	0		0		0		0		ns
SCLK rising edge → Effective data hold	t_{SRD}		$t_{SCY} - 2x - 150$		428 μ s		970		550	ns

Note: System clock is fs, or input clock to prescaler is divisor clock of fs.



(2) UART mode (SCLK0 and SCLK1 external input)

Parameter	Symbol	Variable		32.768 kHz (Note)		12.5 MHz		20 MHz		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
SCLK cycle	t_{SCY}	4x + 20		122 μ s		340		220		ns
SCLK low level pulse width	t_{SCYL}	2x + 5		6 μ s		165		105		ns
SCLK high level pulse width	t_{SCYH}	2x + 5		6 μ s		165		105		ns

Note: System clock is fs, or input clock to prescaler is divisor clock of fs.

4.5 AD Converter Characteristics

($V_{SS} = 0\text{ V}$, $AV_{CC} = V_{CC}$, $AV_{SS} = V_{SS}$, $T_a = -40\text{ to }85^\circ\text{C}$)

$AV_{CC} = V_{CC}$, $AV_{SS} = V_{SS}$

Parameter	Symbol	Condition	Min	Typ.	Max	Unit	
Analog reference voltage (+)	V_{REFH}	$V_{CC} = 5\text{ V} \pm 10\%$	$V_{CC} - 1.5\text{ V}$	V_{CC}	V_{CC}	V	
		$V_{CC} = 3\text{ V} \pm 10\%$	$V_{CC} - 0.2\text{ V}$	V_{CC}	V_{CC}		
Analog reference voltage (-)	V_{REFL}	$V_{CC} = 5\text{ V} \pm 10\%$	V_{SS}				
		$V_{CC} = 3\text{ V} \pm 10\%$	V_{SS}				
Analog input voltage range	V_{AIN}		V_{REFL}		V_{REFH}		
Analog current for analog reference voltage <VREFON> = 1	I_{REF} ($V_{REFL} = 0\text{ V}$)	$V_{CC} = 5\text{ V} \pm 10\%$		1.6	2.0		mA
		$V_{CC} = 3\text{ V} \pm 10\%$		1.0	1.5		
<VREFON> = 0		$V_{CC} = 2.7\sim 5.5\text{ V}$		0.02	5.0	μA	
Error (Not including quantizing errors)	-	$V_{CC} = 5\text{ V} \pm 10\%$		± 1.0	± 3.0	LSB	
		$V_{CC} = 3\text{ V} \pm 10\%$		± 1.0	± 5.0		

Note 1: $1\text{LSB} = (V_{REFH} - V_{REFL})/2^{10}$ [V]

Note 2: Minimum operation frequency.

The operation of the AD converter is guaranteed only when f_c (High-frequency oscillator) is used. (It is not guaranteed when f_s is used.) Additionally, it is guaranteed when the clock frequency which is selected by the clock gear is 4 MHz or more.

Note 3: The value I_{CC} includes the current which flows through the AV_{CC} pin.

4.6 LCD Driver Characteristics

Charge and Pump Characteristics	Symbol	Min	Typ.	Max	Unit
Reference input voltage	V_{L1}	0.9		1.83	V
Output voltage V2 pin	V_{L2}		$2 \times V_{L1}$		
V3 pin	V_{L3}		$3 \times V_{L1}$		
External capacity C0, C1	C_{PMP}	0.1		1.0	μF
V1 pin	C_{VL1}	0.1		1.0	
V2 pin	C_{VL2}	0.1		1.0	
V3 pin	C_{VL3}	0.1		1.0	

Note: Output voltage and External capacity are not loaded.

4.7 Event Counter (TI0, TI2, TI4, TI6, TI8 to TIB)

Parameter	Symbol	Variable		12.5 MHz		20 MHz		Unit
		Min	Max	Min	Max	Min	Max	
Clock cycle	t_{VCK}	$8X + 100$		740		500		ns
Low level clock pulse width	t_{VCKL}	$4X + 40$		360		240		ns
High level clock pulse width	t_{VCKH}	$4X + 40$		360		240		ns

4.8 Interrupt and Capture

(1) \overline{NMI} , INT0 to INT4 interrupts and INTKEY interrupt

Parameter	Symbol	Variable		12.5 MHz		20 MHz		Unit
		Min	Max	Min	Max	Min	Max	
Low level pulse width	t_{INTAL}	$4X$		320		200		ns
High level pulse width	t_{INTAH}	$4X$		320		200		ns

(2) INT7 to INTB interrupts and capture

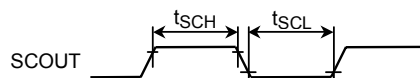
Parameter	Symbol	Variable		12.5 MHz		20 MHz		Unit
		Min	Max	Min	Max	Min	Max	
Low level pulse width	t_{INTBL}	$4X + 100$		420		300		ns
High level pulse width	t_{INTBH}	$4X + 100$		420		300		ns

4.9 SCOUT Pin AC Characteristics

Parameter	Symbol	Variable		12.5 MHz		20 MHz		Unit
		Min	Max	Min	Max	Min	Max	
High level pulse width $V_{CC} = 5V \pm 10\%$	t_{SCH}	$0.5X - 10$		30		15		ns
High level pulse width $V_{CC} = 3V \pm 10\%$		$0.5X - 20$		20		-	-	
Low level pulse width $V_{CC} = 5V \pm 10\%$	t_{SCL}	$0.5X - 10$		30		15		ns
Low level pulse width $V_{CC} = 3V \pm 10\%$		$0.5X - 20$		20		-	-	

Measurement condition

- Output level: High 2.2 V/Low 0.8 V, $C_L = 10$ pF

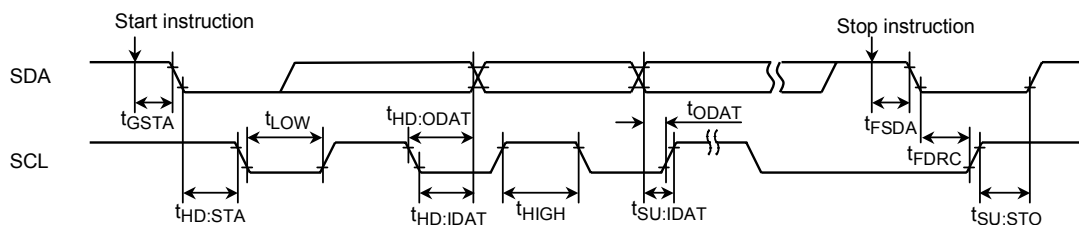


4.10 Timing Chart for Serial Bus Interface

(1) I²C bus mode

Parameter	Symbol	Variable			Unit
		Min	Typ.	Max	
START instruction → SDA falling edge	t _{GSTA}	3X			s
Start condition hold time	t _{HD:STA}	2 ⁿ X			s
SCL low level pulse width	t _{LOW}	2 ⁿ X			s
SCL high level pulse width	t _{HIGH}	2 ⁿ X + 12X			s
Data hold time (Input)	t _{HD:IDAT}	0			ns
Data setup time (Input)	t _{SU:IDAT}	250			ns
Data hold time (Output)	t _{HD:ODAT}	7X		11X	s
Data valid → SCL rising edge	t _{ODAT}		2 ⁿ X - t _{HD:ODAT}		s
STOP instruction → SDA falling edge	t _{FSDA}	3X			s
SDA falling edge → SCL rising edge	t _{FDRC}	2 ⁿ X			s
Stop condition hold time	t _{SU:STO}	2 ⁿ X + 16X			s

Note: SBICR1<SCK2:0> sets n.



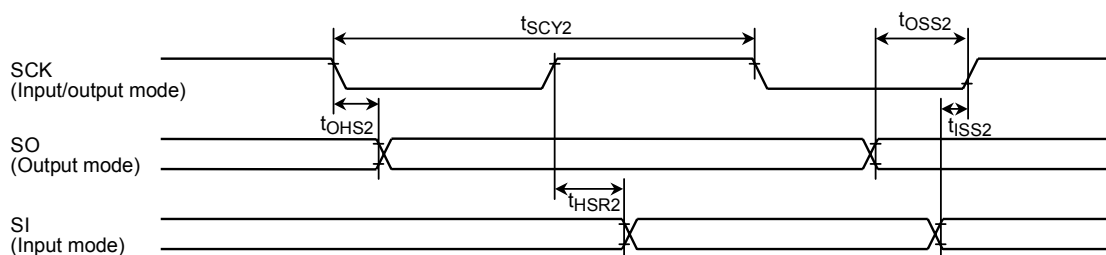
(2) Clock-synchronous 8-bit SIO mode (Serial bus interface) clock

1. SCK input mode

Parameter	Symbol	Variable		Unit
		Min	Max	
SCK cycle	t_{SCY2}	2^9X		s
SCK falling edge → Output data hold	t_{OHS2}	$6X$		s
Output data → SCK rising edge	t_{OSS2}	$t_{SCY2} - 6X$		s
SCK rising edge → Input data hold	t_{HSR2}	$6X$		ns
Input data → SCK rising edge	t_{ISS2}	0		ns

2. SCK output mode

Parameter	Symbol	Variable		Unit
		Min	Max	
SCK cycle	t_{SCY2}	2^5X	$2^{11}X$	s
SCK falling edge → Output data hold	t_{OHS2}	$2X$		s
Output data → SCK rising edge	t_{OSS2}	$t_{SCY2} - 2X$		s
SCK rising edge → Input data hold	t_{HSR2}	$2X$		s
Input data → SCK rising edge	t_{ISS2}	0		ns



4.11 Operation in PROM Mode

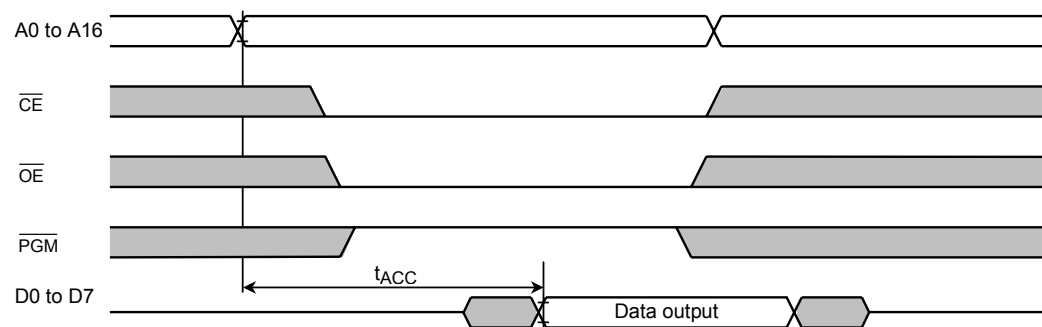
(1) DC and AC characteristics in read operation

$T_a = 25 \pm 5^\circ\text{C}$ $V_{CC} = 5\text{V} \pm 10\%$

Parameter	Symbol	Condition	Min	Max	Unit
V_{PP} read voltage	V_{PP}	-	4.5	5.5	V
Input high voltage (A0 to A16, \overline{CE} , \overline{OE} , \overline{PGM})	V_{IH1}	-	2.2	$V_{CC} + 0.3$	
Input low voltage (A0 to A16, \overline{CE} , \overline{OE} , \overline{PGM})	V_{IL1}	-	-0.3	0.8	
Address to output delay	t_{ACC}	$C_L = 50\text{ pF}$	-	$2.25 T_{CYC} + \alpha$	ns

$T_{CYC} = 400\text{ ns}$ (10 MHz clock)

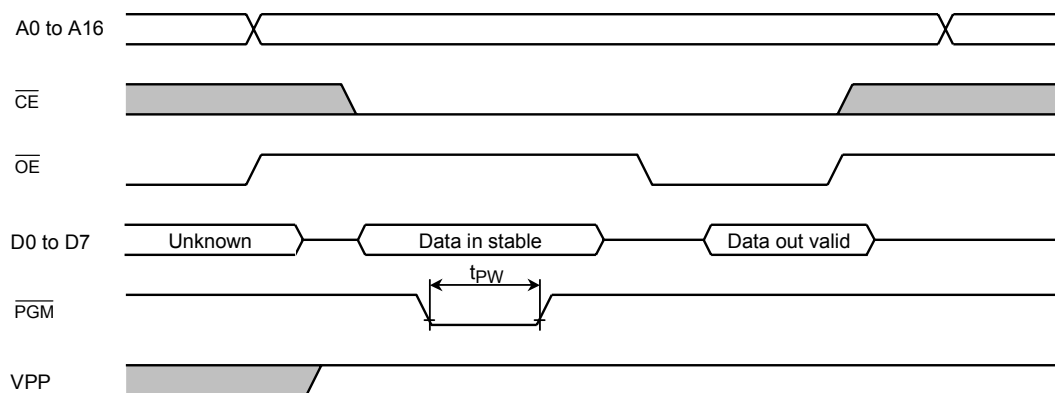
$\alpha = 200\text{ ns}$



(2) DC and AC characteristics in programming

 $T_a = 25 \pm 5^\circ\text{C}$ $V_{CC} = 6.25\text{ V} \pm 0.25\text{ V}$

Parameter	Symbol	Condition	Min	Typ.	Max	Unit
Programming supply voltage	V_{PP}	–	12.50	12.75	13.00	V
Input high voltage (D0 to D7, A0 to A16, \overline{CE} , \overline{OE} , \overline{PGM})	V_{IH}	–	2.6		$V_{CC} + 0.3$	
Input low voltage (D0 to D7, A0 to A16, \overline{CE} , \overline{OE} , \overline{PGM})	V_{IL}	–	–0.3		0.8	
V_{CC} supply current	I_{CC}	$f_c = 10\text{ MHz}$	–		50	mA
V_{PP} supply current	I_{PP}	$V_{PP} = 13.00\text{ V}$	–		50	
\overline{PGM} program pulse width	t_{PW}	$C_L = 50\text{ pF}$	0.095	0.1	0.105	ms



Note 1: The power supply of V_{PP} (12.75 V) must be turned on at the same time or the later time for a power supply of V_{CC} and must be turned off at the same time or early time for a power supply of V_{CC} .

Note 2: The device suffers a damage taking out and putting in on the condition of $V_{PP} = 12.75\text{ V}$.

Note 3: The maximum spec of V_{PP} pin is 14.0 V. Be carefull a overshoot at the programming.

5. Port Section Equivalent Circuit Diagram

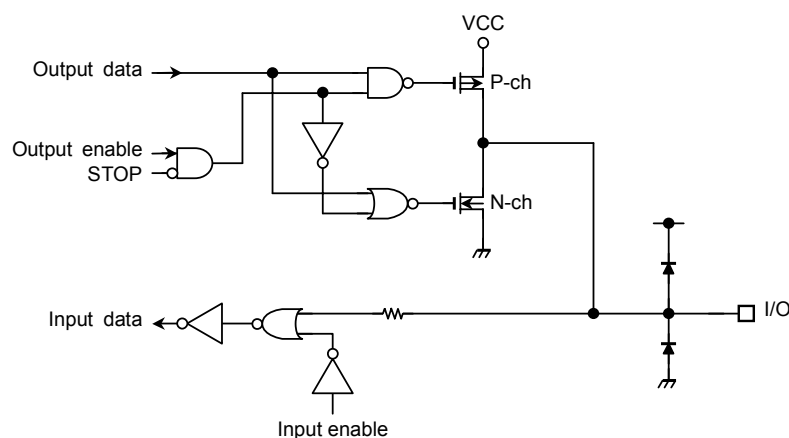
- Reading the circuit diagram

Basically, the gate symbols written are the same as those used for the standard CMOS logic IC [74HCXX] series.

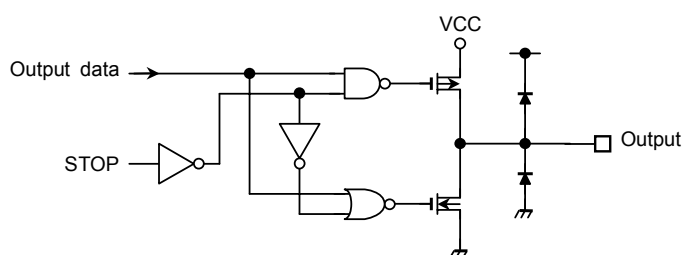
The dedicated signal is described below.

Stop: This signal becomes active 1 when the HALT mode setting register is set to the Stop mode and the CPU executes the HALT instruction. When the drive enable bit [DRVE] is set to 1, however, Stop remains at 0.

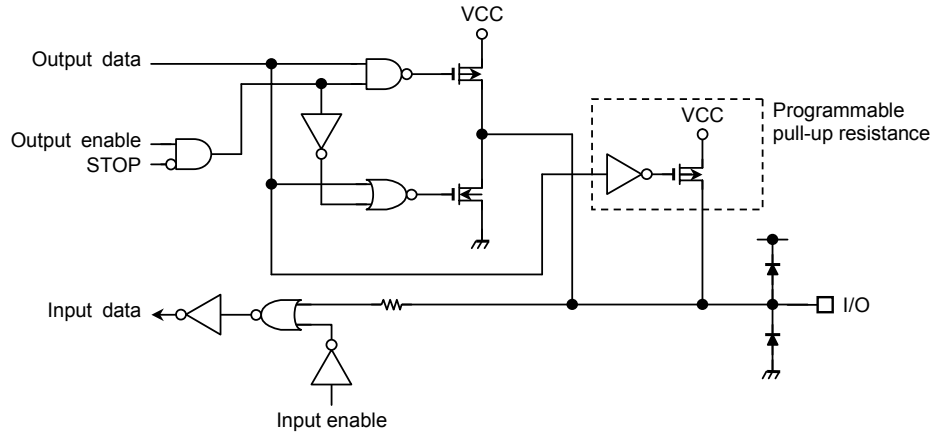
- The input protection resistance ranges from several tens of ohms to several hundreds of ohms.
 - P0 (AD0 to AD7), P1 (AD8 to AD15, A8 to A15), and P67 (TO1)



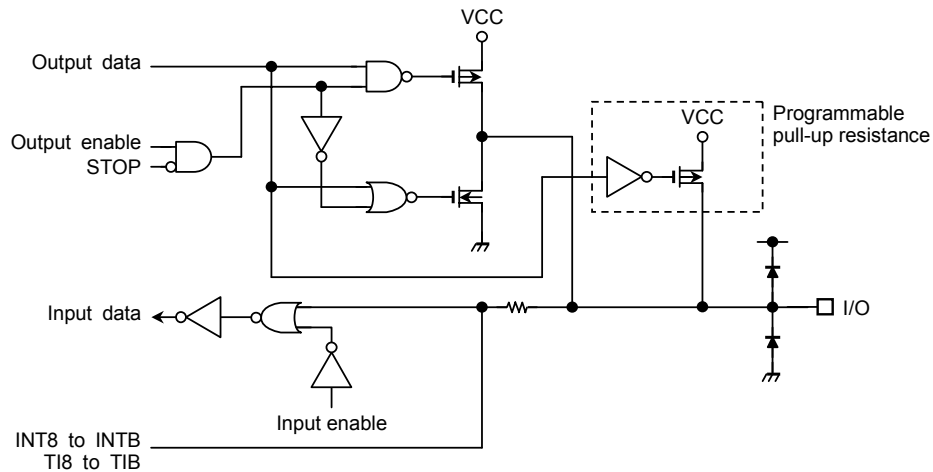
- P30 (\overline{RD}) and P31 (\overline{WR})



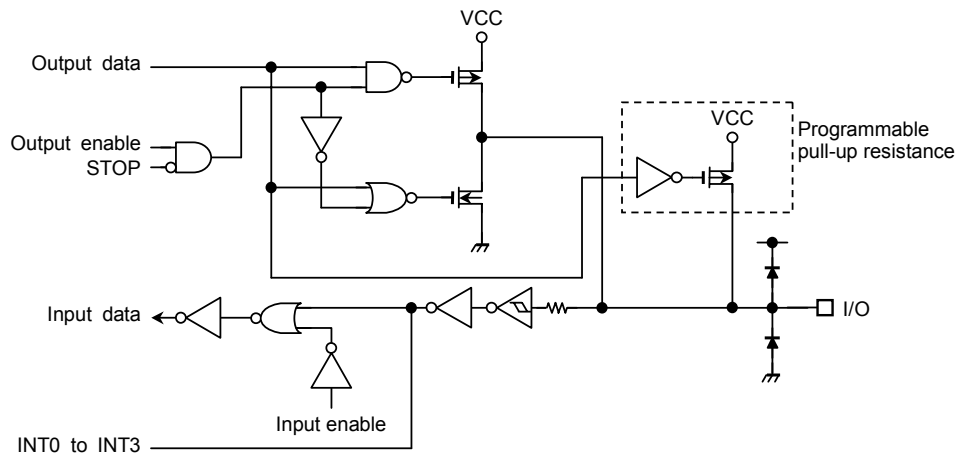
■ P2 (A16 to A23, A0 to A7), P32 (HWR), P72 (TO8), P73 (SCOUT), and P76 (TOA)



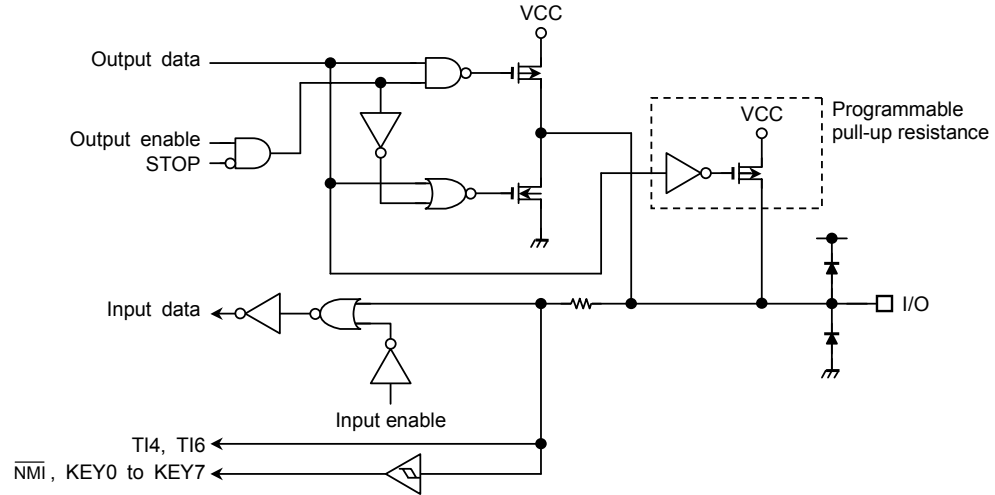
■ P70 (TI8/INT8), P71 (TI9/INT9), P74 (TIA/INTA), and P75 (TIB/INTB)



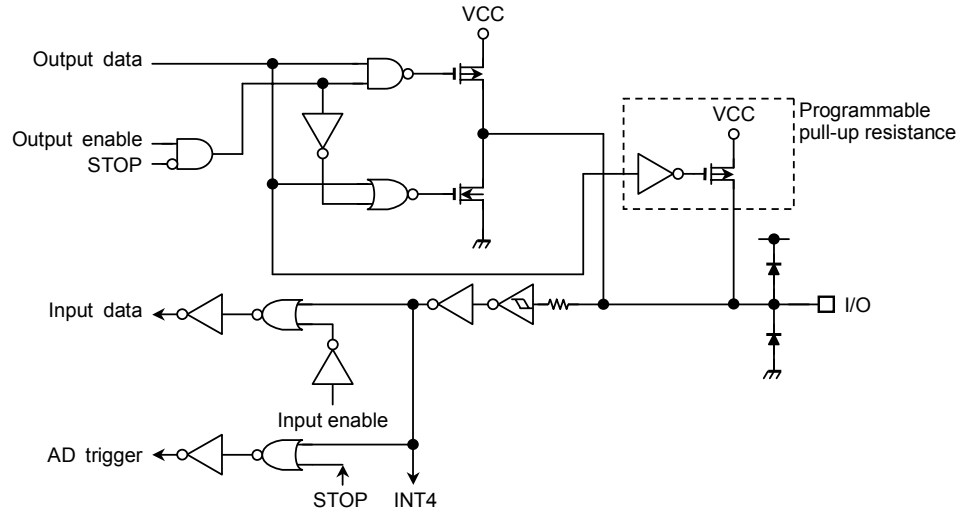
■ P33 to P36 (INT0 to INT3)



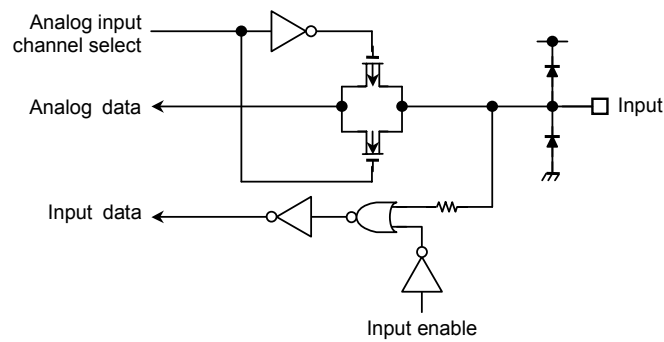
■ P4 (TI_x, TO_x, KEY_x) and P77 ($\overline{\text{NMI}}$)



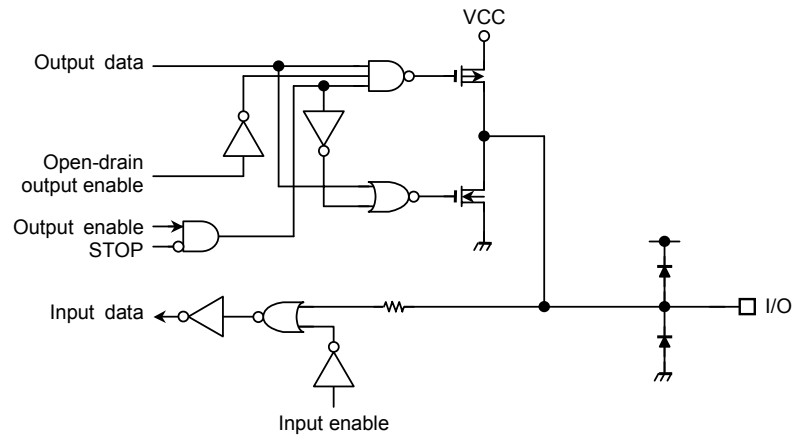
■ P37 (INT4/ $\overline{\text{ADTRG}}$)



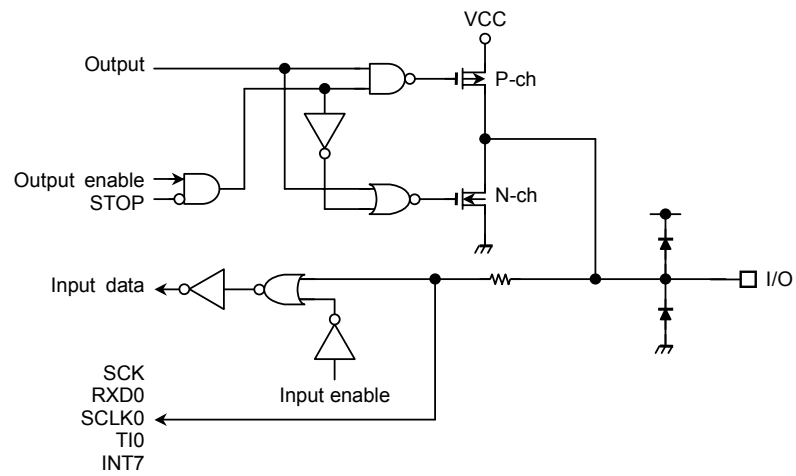
■ P5 (AN0 to AN7)



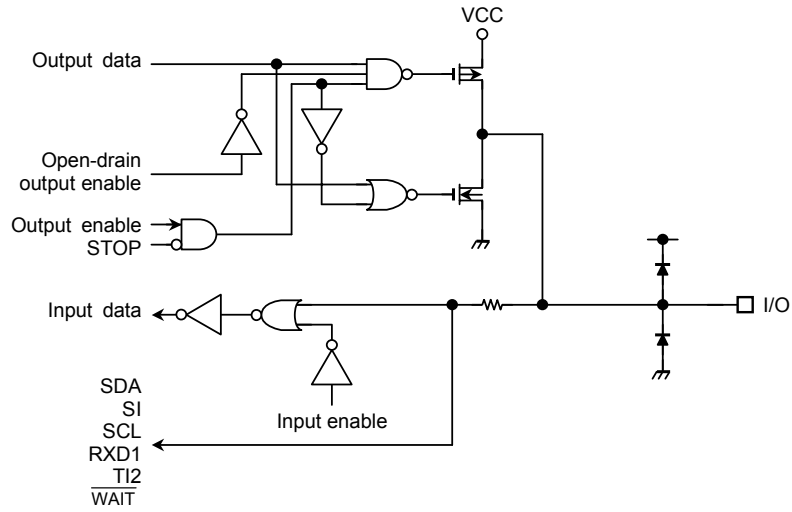
■ P63 (TXD0), P80 (TXD1), P83 (TO3), and P85



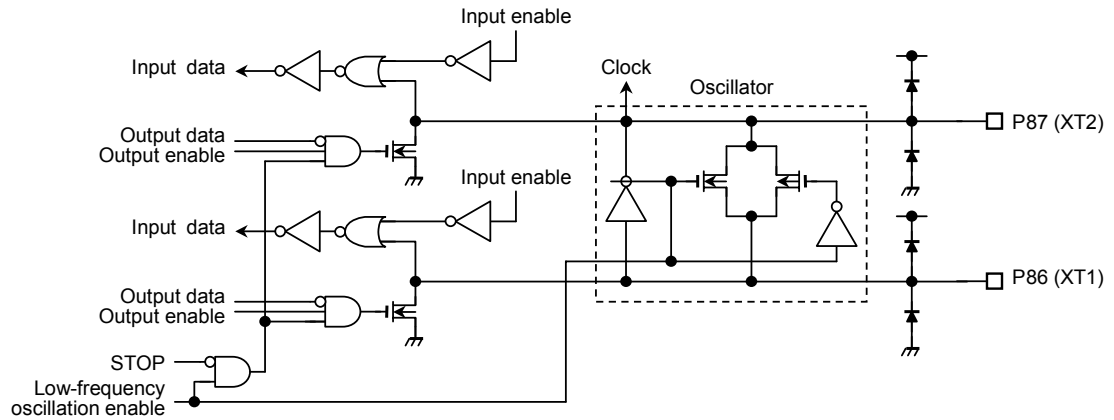
■ P60 (SCK), P64 (RXD0), P65 (SCLK0), and P66 (TI0/INT7)



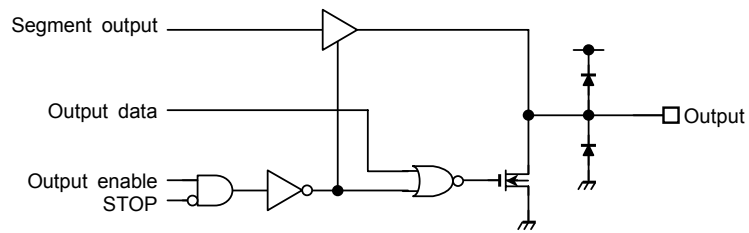
- P61 (SO/SDA), P62 (SI/SCL), P81 (RXD1), P82 (TI2), and P84 ($\overline{\text{WAIT}}$)



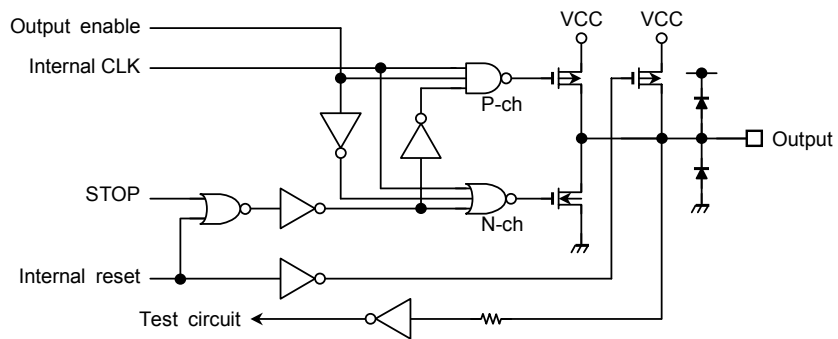
- P86 (XT1) and P87 (XT2)



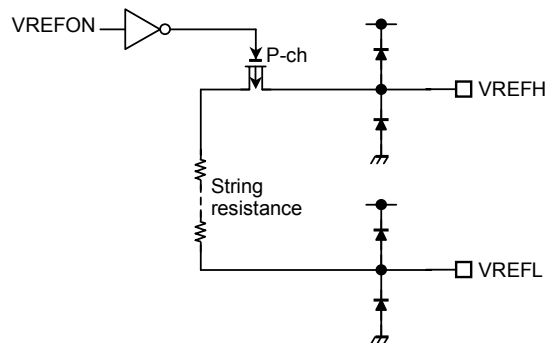
■ P90 to P97 (SEG24 to SEG31), PA0 to PA7 (SEG32 to SEG39)



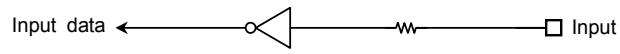
■ CLK



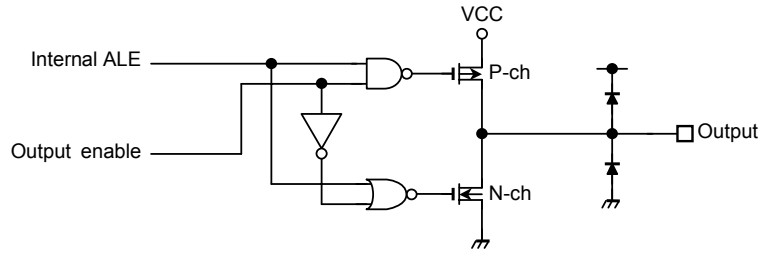
■ VREFH and VREFL



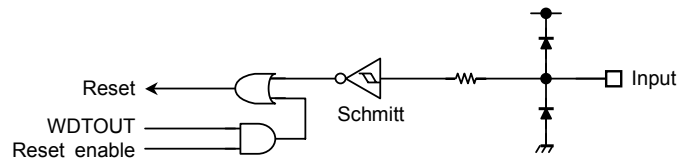
■ \overline{EA}



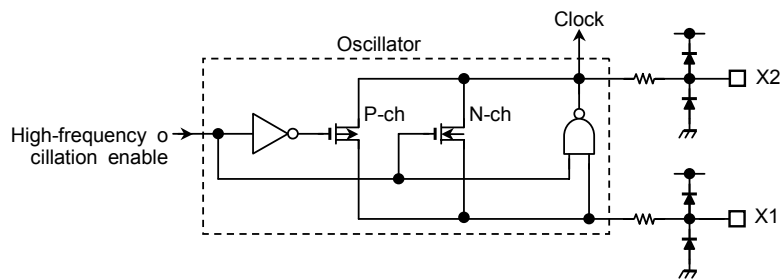
■ ALE



■ \overline{RESET}



■ X1 and X2



6. Package Dimensions

P-LQFP144-1616-0.40

Unit: mm

